

What is claimed is:

1. A temperature-compensated crystal oscillator comprising:  
a substrate having a circuit pattern disposed on a surface thereof and  
mounting electrodes disposed on a reverse side thereof and electrically  
connected to said circuit pattern;  
5 circuit components mounted on the surface of said substrate and  
electrically connected to said circuit pattern; and  
a surface-mount crystal unit having a hermetically sealed crystal blank,  
and mounted on the surface of said substrate and electrically connected to said  
circuit pattern;  
10 said crystal blank having a cavity defined in a mounting surface thereof,  
at least one of said circuit components being housed in said cavity.
2. The temperature-compensated crystal oscillator according to claim 1,  
further comprising a temperature-compensating circuit, said temperature-  
compensating circuit comprising circuit components housed in said cavity.
3. The temperature-compensated crystal oscillator according to claim 2,  
wherein said temperature-compensating circuit is directly connected to said  
crystal unit, whereby the temperature-compensated crystal oscillator serves as  
a temperature-compensated crystal oscillator of the direct compensation type.
4. The temperature-compensated crystal oscillator according to claim 2,  
further comprising an adjusting capacitor for equalizing an oscillation frequency  
at a predetermined temperature to a target frequency, said adjusting capacitor

being mounted on the surface of said substrate and disposed outside of said  
5 cavity.

5. The temperature-compensated crystal oscillator according to claim 1,  
wherein said circuit components which are disposed in said cavity comprise  
chip-type circuit components each having a size of 0.6 mm × 0.3 mm.

6. The temperature-compensated crystal oscillator according to claim 2,  
further comprising a variable capacitance diode for changing an oscillation  
frequency depending on a control voltage supplied from an external circuit, said  
variable capacitance diode being mounted on the surface of said substrate and  
5 disposed outside of said cavity.